

MX1-10FEP

Fanless Embedded System
Supports Intel® Coffee Lake Xeon / Core-i Powerful Processor

Introduction

MITAC's MX1-10FEP embedded system is the next generation embedded system with Intel® Coffee Lake C246 workstation chipset which can support Xeon and Core-i LGA1151 socket type processor. The excellent performance, powerful processor, OCP/OVP power protection, and expandable design provide the solution for every complicated task and most types of application.

The MX1-10FEP's 7.8 liter fan-less chassis design and Xpandable module design give it the possibility to implement the complicated tasks and for every workspace and environment. VESA mount holes allow for space-saving and rear-mounting on VESA arms. Flexibilities also mean a rich array of I/O ports (including 2 x Ethernet RJ45, 8 x USB, 1 x HDMI, 1 x DVI-I, 1 x DisplayPort, 2 x COM, PCIe X16 slot, 3-pin Terminal Block Power Input, and 3 x Expansion doors) to add a variety of peripherals. Storage expandability is supported for 3 x high-density hard drives in 2.5" HDD bracket design. Two mPCIe (shared with mSATA) slots provide the support of SSD and wireless interfaces which allow effortless connection to Wi-Fi and Bluetooth networks, and 4Gconnectivity. DIO/COM/LAN/PoE/Power Ignition expansion modules extend the capability and possibility to be used in more applications.

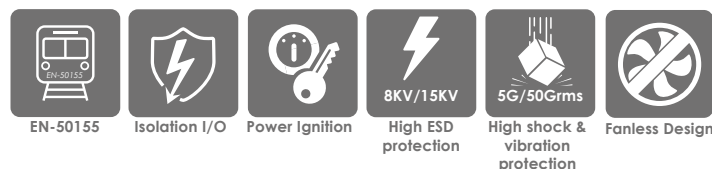


Optional Peripheral

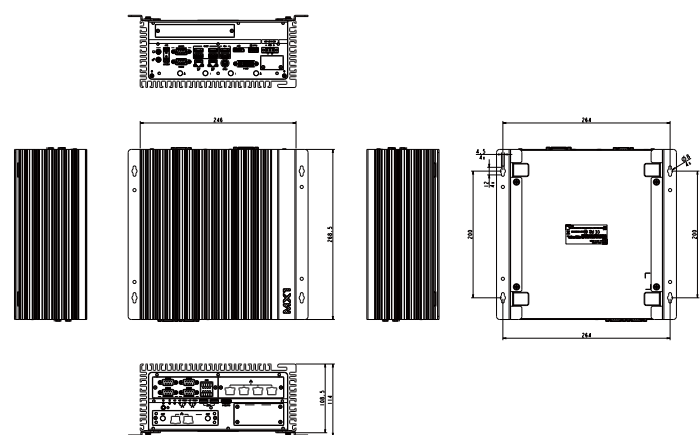
Model Number	Description
MS-48CDN-DT10	Xpansion Module with 4 x RS232 / 422 / 485, 8-bit Isolated DIDO (4 x DI, 4 x DO)
MS-04LAN-R10	Xpansion Module with 4 x Intel i210-IT Giga LAN, RJ45 Port
MS-04LAN-M10	Xpansion Module with 4 x Intel i210-IT Giga LAN, M12 Port
MS-04POE-R10	Xpansion Module with 4 x PoE+, Intel i210-IT Giga LAN, RJ45 Port
MS-04POE-M10	Xpansion Module with 4 x PoE+, Intel i210-IT Giga LAN, M12 Port
ME-02POE-R10	Xpansion Module with 2 x PoE+, Intel i210-IT Giga LAN, RJ45 Port
MS-01IGN-S10	Vehicle Power Ignition Card, 12V/24V and Power ON/OFF Timing Selectable
220W Power Adapter	AC to DC, DC24V / 9.2A, 220W*
300W Power Adapter	AC to DC, DC24V / 12.5A, 300W*

* Safety Operating: 0~40°C, practical Operating: -30~60°C (Over 40°C need derating by 2.5%/°C).

* AC to DC Accessory for industrial application. Not for railway application



Dimension (mm)



MX1-10FEP Fanless Embedded System

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MITAC COMPUTING TECHNOLOGY CORP.

SYSTEM	
CPU	9th & 8th Gen Intel® Coffee Lake Xeon LGA1151 Socket Processor, 6-core TDP Max. 80W 9th & 8th Gen Intel® Coffee Lake LGA1151 Socket Processor, Core i7/i5/i3 6-core TDP Max. 65W, Core i9 8-core TDP Max 35W
Chipset	Intel® C246
System Memory	DDR4 2666MHz, 2 x 260-pin SO-DIMM, Max. 32GB (Xeon: ECC; Core-i: Non-ECC)
Graphics	Intel® HD Graphics
Display Interface	HDMI, DisplayPort, DVI-I
Storage Slot	3 x 2.5 HDD / SSD (1 w/ Removable HDD Bay, 2 w/ Internal HDD Bracket) 2 x mSATA
Ethernet	Intel® I219-LM Giga LAN + I210-IT Giga LAN
Audio	Realtek® ALC662
I/O Chipset	Nuvoton NCT6116D
TPM	Nuvoton NPCT750AAAYX
Expansion Slot	Storage: M.2 2242 / 2260 / 2280 M key (PCIe X4 / SATA) Storage/LTE/Wireless: 2 x Mini PCIe Full / Half size (USB / PCIe / SATA), w/ SIM Card Holder Wireless: M.2 2230 E key (PCIe / USB) PCIe 3.0 X16
Indicator	Power LED, HDD LED, DIO LED, LAN1 & 2 ACT / SPEED
FRONT I/O	2 x USB 3.0 1 x HDMI 1.4 2 x SIM Card Slot w/ Cover 1 x 2.5" SATAIII HDD / SSD Bay
REAR I/O	4 x USB 3.1 Gen 2 (Gbps), 2 x USB 2.0, 2 x RJ-45, 1 x DisplayPort 1.2, 1 x DVI-I, 1 x PS/2 2 x RS232 / 422 / 485 (Support Power 5V / 12V), 1 x Mic-in, 1 x Line-out 1 x 2-pin Terminal Block Remote Power on / off 1 x 2-pin Terminal Block Remote Power reset 1 x 4-pin Terminal Block External Fan Connector 1 x 3-pin Terminal Block Power Input 4 x SMA Antenna (Optional for WiFi/LTE function)
H/W Monitor	-
Watchdog Timer	1~255 Steps by Software Program
POWER REQUIREMENT	
Power Input	9~48V Wide Range DC Input w/ Terminal Block Connectivity
MECHANICAL	
Thermal Design	Fanless
Mounting	Wallmount
Dimension	10.6" x 9.7" x 4.3" (268 mm x 246 mm x 108 mm)
Material	Top cover: Aluminum Alloy, Bezel and chassis: Steel
ENVIRONMENTAL	
Operating Temperature	35W TDP Processor: -40°C to 70°C (with 0.7m/s Air Flow and Wide Temperature Memory/Storage) 51~65W TDP Processor: -40°C to 50°C (with 0.7m/s Air Flow and Wide Temperature Memory/Storage) 71~80W TDP Processor: -40°C to 40°C
Operating Humidity	10%~90% R/H (Non-condensing)
Vibration Resistance	Operating, 5 Grms, 5-500 Hz, 3 Axes (w/ SSD, according to IEC60068-2-64)
Shock Resistance	Operating, 50 Grms, Half-sine 11 ms Duration (w/ SSD, according to IEC60068-2-27)
Certification	EMC: CE & FCC Safety: compliant with LVD, EN60950-1 / EN62368-1 Compliant with EN50155/EN50121/E-mark
OS	
OS Support	Windows® 10 64-bit, Linux (support by request)

Ordering Information

Model Number	Chipset	HDMI / DP / DVI-I	USB 3.0 / 2.0	COM	LAN	mSATA & mPCIe / M.2 E Key / M.2 M Key	Mic-in / Line-out	Power
MX1-10FEP-C246	C246	1 / 1 / 1	6 / 2	2	2	2 / 1 / 1	1 / 1	9~48V Wide Range DC Input w/ Terminal Block Connectivity

Packing List

Packing		
• 1 x MX1-10FEP	• 1 x 3-pin Terminal Block Connector	• 1 x 4-pin Terminal Block Connector
• 1 x CPU Cooler (passive)	• 1 x DVI to VGA converter	• 1 x Wall Mount Bracket
• 1 x Screw Pack (For HDD)	• 2 x 2-pin Terminal Block Connector	• 1 x Driver CD